Recent Exemptions, March 2005 (Pb)

- Lead in solders for servers, storage, and network equipment
  - Time limited exemption, year 2010, has been removed (paragraph 7)
- Lead in compliant pin and press-fit connector systems
  - Concern about tin whiskers, but disagreement among manufacturers
- Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight (exemption until 2010)
  - Request seems to have been specific to one manufacturer
- Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages
  - SUSS MicroTec and IBM have released a lead-free solder bumping process, C4NP (www.suss.com/main.php?rad_id=729)
- Lead in safety equipment for fire and rescue services
  - Insufficient technical justification; rejected

Current Requests for Exemptions (Pb)

- To be voted on in February/March 2005
  - Lead in tin whisker resistant coatings for fine pitch applications,
  - Solders containing lead and/or cadmium for specific applications
    - Refers to a thermal sensing element
  - Lead in lead oxide glass plasma display panels,
  - Lead in connectors, flexible printed circuits, flexible flat cables,
  - Lead oxide in lead glass, bonding materials of magnetic heads and magnetic heads,
  - Lead in optical isolators,
  - Lead in low melting point alloys (< $175^{\circ}C$),
  - Lead in solder in parts recovered from production printers and copying equipment within the original manufacturer's closed loop system until July 2011
  - Lead in electrical equipment in the aeronautic and aerospace sectors that requires high safety standards
- Future exemptions unlikely
  - Must come with all necessary independent scientific evidence to support the proposed exemption